

What is claimed is:

1. A method for manufacturing pins, comprising:
punching out at least one pin from a basic body by at
5 least one punching process step; and
coating the pin or a section of the pin with a separate
metal layer after completion of the punching out of the pin.
2. The method according to claim 1, wherein the front face
10 at an outer end section of the pin is coated with the metal
layer.
3. The method according to claim 1, wherein at least one
metal deposition process step is used for coating the pin
15 with the separate metal layer.
4. The method according to claim 1, further comprising
mounting the basic body in a housing.
- 20 5. The method according to claim 4, wherein the mounting
of the basic body in the housing takes place prior to com-
pletion of the punching out of the pin.
6. The method according to claim 1, wherein a plurality of
25 pins positioned side by side are punched out from the basic
body.
7. The method according to claim 6, wherein the pins posi-
tioned side by side are coated with a separate metal layer
30 after completion of the punching out of the pins.

8. The method according to claim 6, wherein at least one of the plurality of pins positioned side by side is coated with a separate metal layer after completion of the punching out of the corresponding pin, and wherein the coating with a
5 separate metal layer is performed with the remaining pins prior to completion of the punching out of the respective pins.

9. The method according to claim 8, wherein the at least
10 one pin is, with respect to the remaining pins, positioned side by side, and positioned further outside or outermost.

10. A semiconductor device pin configured to be manufactured by punching and/or metal coating processes from a basic body, wherein a finished condition of the pin, and a
15 front face at an outer pin end section is coated with a separate metal layer.

11. A housing for semiconductor devices, comprising:
20 a plurality of pins configured to be manufactured by punching and/or metal coating processes from a basic body, wherein at least one pin, in a finished condition, has a front face at an outer pin end section coated with a separate metal layer.

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12. A method according to claim 3, wherein, for carrying out the deposition process steps, a galvanizing potential is generated at the pin by a corresponding voltage being applied at a further pin and/or side web connected with the
30 pin internally via the corresponding semiconductor device.

13. A method according to claim 3, wherein, for performing the deposition process steps, a galvanizing potential is generated at the pin by a corresponding voltage being applied at the basic body connected with the pin internally
5 via the corresponding semiconductor device.

14. The method according to claim 1, wherein the basic body is a lead frame.

10 15. The method according to claim 3, wherein the deposition process step is a galvanizing process step.

16. The method according to claim 4, wherein the housing is a semiconductor device housing.